

Q7800 Automatic Wedge Bonder

Designed for Complex Hybrid, Opto-Electronic and I.C. Assembly Requirements

Specifications*

Standard Features – Hardware

30° Rotary Bond Head
On Axis Linear Theta Encoder
4" X 3.65" Table Travel
Programmable U/S Generator
Solid State Vision System
Matrox Pattern Recognition System
Flat Panel Monitor
Stereo Zoom 4 Microscope
Wireless Mouse
Galil Motion Control System
Windows™ XP OS
Fiber Optic Light Source

Specifications

Aluminum or Gold Wire
Size Range
0.0007" – 0.003" (17.8 – 76.2 microns)
Maximum Wires Per Device
Unlimited
Spool Diameter
2.0" (50.8)
Wire Feed Angle
30°, 38°, 45°, or 60°

Bonding Speed per Wire
(30° Standard Bond Head)
550 - 750 ms

XY Table
Resolution
± 0.0000625" (1.6 microns)
Bonding Pitch
± 0.00275" (69.9 microns)

Point and Click Bond Targeting
Simple, Intuitive Programming
Easy Bond Process Editing
Extensive Program Storage
Bond Parameter Library
Unlimited Wire Program Storage
Multiple Stitch Bonding
Program Wire Groups for Multi-device,
High Wire Count Hybrids

Options

Custom Wire Profiles
Programmable Temperature Controller
Deep Access 60° - Table Tear
High Frequency U/S Generator / Transducer
Manual Workholder
Heated Manual Workholder

Accessories

Ethernet Adapter for Networking Bonders
Additional Fiber Optic Light Source

Miscellaneous

Remote Diagnostics Capability
CE Mark

Facilities

Electric 120 VAC, 50/60 Hz, 20A
N2 or clean, dry air
Vacuum / Air as required for workholder

Dimension/Weight

Height: 72" (183 cm)
Width: 39" (99 cm)
Depth: 34.5" (88 cm)
Table Height: 40" (102 cm)
Weight: 600 pounds (273 Kg)
Crated Weight: 750 pounds (341 Kg)

* Subject to Change

01/01/11

Standard Features – Software